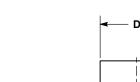


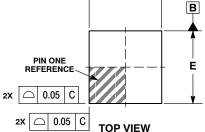


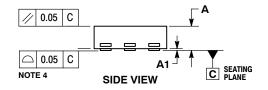
XDFN6 1.20x1.20, 0.40P CASE 711AH ISSUE O

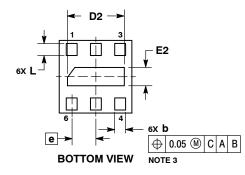
Α

DATE 14 SEP 2011









NOTES 1. DIMENSIONING AND TOLERANCING PER

ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: MILLIMETERS.

DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 3.

COPLANARIZE AND IS MEASURED BETWEEN 0.15 AND 0.25mm FROM TERMINAL TIPS.
COPLANARITY APPLIES TO ALL OF THE TERMINALS

IERMINALS.			
	MILLIMETERS		
DIM	MIN	MAX	
Α		0.40	
A1	0.00	0.05	
b	0.13	0.23	
D	1.20 BSC		
D2	0.89	0.99	
Е	1.20 BSC		
E2	0.25	0.35	
е	0.40 BSC		
L	0.15	0.25	
L1	0.05 BSC		

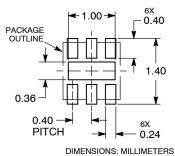
GENERIC **MARKING DIAGRAM***

XX MM 0

XX = Specific Device Code MM = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

RECOMMENDED **MOUNTING FOOTPRINT***



*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	XDFN6, 1.20 X 1.20, 0.40P		PAGE 1 OF 1	
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